

**Product / Package Information**

Package	WLCSP
Body Size	
I/O Count	49
Terminal Finish	SnAgCu
MS Number	MS012787A

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes
Last Updated	5-Jul-19

**Materials Declaration**

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.21E-02	100.00	1000000	68.07	680701

**Wafer Bumps**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.92E-03	95.50	955000	27.59	275881
Tin & its alloys	Silver	7440-22-4	2.06E-04	4.00	40000	1.16	11555
Tin & its alloys	Copper	7440-50-8	2.58E-05	0.50	5000	0.144	1444
Subtotal			5.15 E-03	100.00	1000000	28.89	288880

**UBM / RDL**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.76 E-04	99.06	990595	2.11	21075
Other non-ferrous metals and alloys	Titanium	7440-32-6	3.57 E-06	0.94	9405	0.020	200
Subtotal			3.80 E-04	100.00	1000000	2.13	21275

**Polyimide**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Resin	Proprietary	1.11 E-04	67.95	679500	0.62	6213
Other organic materials	Tetraethylene Glycol Dimethacrylate	109-17-1	2.37 E-05	14.56	145600	0.133	1331
Other organic materials	Trifluoroacetic Anhydride	407-25-0	9.51 E-06	5.83	58300	0.053	533
Other organic materials	4,4'-Oxydiphthalic Anhydride	1823-59-2	9.51 E-06	5.83	58300	0.053	533
Other organic materials	2-Hydroxyethyl Methacrylate	868-77-9	9.51 E-06	5.83	58300	0.053	533
Subtotal			1.63 E-04	100.0	1000000	0.91	9143

Package Totals	Weight (g)	Percentage (%)	PPM
	1.78 E-02	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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